Abstracts

Three-dimensional high-frequency distribution networks. II. Packaging and integration

R.M. Henderson, K.J. Herrick, T.M. Weller, S.V. Robertson, R.T. Kihm and L.P.B. Katehi. "Three-dimensional high-frequency distribution networks. II. Packaging and integration." 2000 Transactions on Microwave Theory and Techniques 48.10 (Oct. 2000 [T-MTT]): 1643-1651.

This paper describes the implementation and packaging of the components, described in Part I of this paper, to realize a three-dimensional W-band distribution network.

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